

Multilayer Ceramic Chip Capacitors

CKG57NX5R1H226M500JH









TDK item description CKG57NX5R1H226MT****

Applications	Commercial Grade	
Feature	Mega MEGACAP Type	
Series	CKG57N(5750) [EIA 2220]	
Status	Production	



	Size
Length(L)	6.00mm ±0.50mm
Width(W)	5.00mm ±0.50mm
Thickness(T)	5.00mm ±0.50mm
Metal-Frame Width(E)	1.60mm ±0.30mm
Recommended Land Pattern (PA)	3.90mm to 4.30mm
Recommended Land Pattern (PB)	1.50mm to 2.00mm
Recommended Land Pattern (PC)	4.50mm to 5.00mm

Electrical Characteristics		
Capacitance	22μF ±20%	
Rated Voltage	50VDC	
Temperature Characteristic	X5R(±15%)	
Dissipation Factor (Max.)	5%	
Insulation Resistance (Min.)	22ΜΩ	

Other		
Soldering Method	Reflow	
AEC-Q200	No	
Packing	Blister (Plastic)Taping [330mm Reel]	
Package Quantity	1000pcs	

[!] Images are for reference only and show exemplary products.

[!] This PDF document was created based on the data listed on the TDK Corporation website.

[!] All specifications are subject to change without notice.

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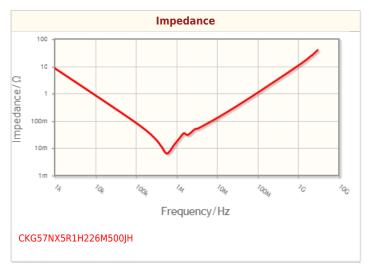


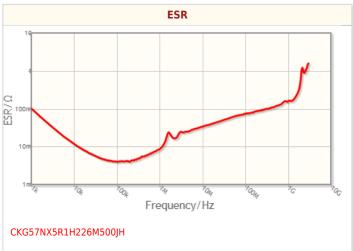


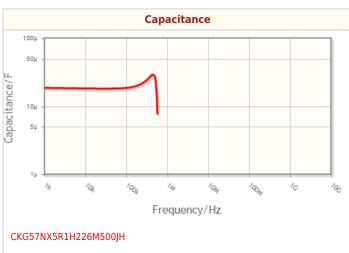


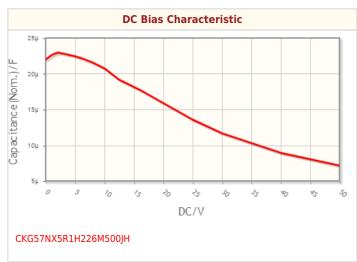


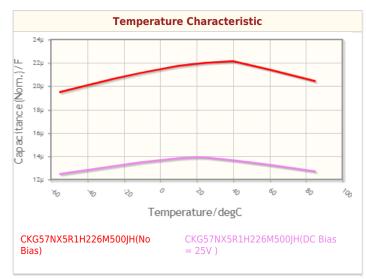
Characteristic Graphs(This is reference data, and does not guarantee the products characteristics.)

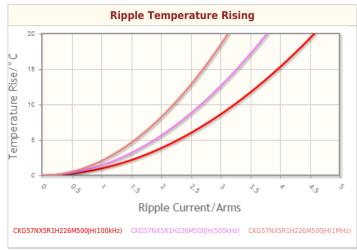












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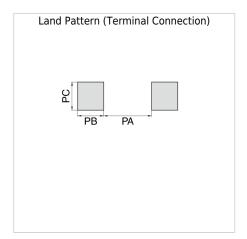








Associated Images



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